



Standard Test Method for In-Plane Length Measurements of Thin, Reflecting Films Using an Optical Interferometer¹

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1. Scope

1.1 This test method covers a procedure for measuring in-plane lengths (including deflections) of patterned thin films. It applies only to films, such as found in microelectromechanical systems (MEMS) materials, which can be imaged using an interferometer.

1.2 There are other ways to determine in-plane lengths. Using the design dimensions typically provides more precise in-plane length values than using measurements taken with an optical interferometer. (Interferometric measurements are typically more precise than measurements taken with an optical microscope.) This test method is intended for use when interferometric measurements are preferred over using the design dimensions (for example, when measuring in-plane deflections and when measuring lengths in an unproven fabrication process).

1.3 This test method uses a non-contact optical interferometer with the capability of obtaining topographical 3-D data sets. It is performed in the laboratory.

1.4 The maximum in-plane length measured is determined by the maximum field of view of the interferometer at the lowest magnification. The minimum deflection measured is determined by the interferometer's pixel-to-pixel spacing at the highest magnification.

1.5 *This standard does not purport to address all of the safety concerns, if any, associated with its use. It is the responsibility of the user of this standard to establish appropriate safety and health practices and determine the applicability of regulatory limitations prior to use.*

2. Referenced Documents

2.1 ASTM Standards:

E 2245 Test Method for Residual Strain Measurements of Thin, Reflecting Films Using an Optical Interferometer²

E 2246 Test Method for Strain Gradient Measurements of Thin, Reflecting Films Using an Optical Interferometer²

3. Terminology

3.1 Definitions:

3.1.1 *2-D data trace, n*—a two-dimensional data trace that is extracted from a topographical 3-D data set and that is parallel to the xz - or yz -plane of the interferometer.

3.1.1.1 *Discussion*—The height of the sample is measured along the z -axis of the interferometer. The interferometer's x -axis (as shown in Figs. 1 and 2) is typically aligned parallel or perpendicular to the transitional edges to be measured.

3.1.2 *3-D data set, n*—a three-dimensional data set with a topographical z -data value for each (x, y) pixel location within the interferometer's field of view.

3.1.3 *anchor, n*—in a surface-micromachining process, the portion of the test structure where the mechanical layer makes contact with the underlying layer (see Fig. 2).

3.1.4 *anchor lip, n*—in a surface-micromachining process, the extension of the mechanical layer around the edges of the anchor (see Fig. 2).

3.1.5 *bulk micromachining, adj*—a MEMS fabrication process where the substrate is removed at specified locations, which can create structures suspended in air.

3.1.6 *cantilever, n*—a test structure that consists of a beam suspended in air and anchored or supported at one end.

3.1.7 *fixed-fixed beam, n*—a test structure that consists of a beam suspended in air and anchored or supported at both ends (see Figs. 1 and 2, and Fig. X1.1).

3.1.8 *in-plane length measurement, n*—a length (or deflection) measurement made parallel to the underlying layer (or the xy -plane).

3.1.9 *interferometer, n*—a non-contact optical instrument (such as shown in Fig. 3) used to obtain topographical 3-D data sets.

3.1.10 *mechanical layer, n*—in a surface-micromachining process, the patterned layer (as shown in Fig. 2) that is anchored to the underlying layer where cuts are designed in the sacrificial layer and that is suspended in air where no cuts are designed in the sacrificial layer.

3.1.11 *MEMS, adj*—microelectromechanical systems.

3.1.12 *sacrificial layer, n*—in a surface-micromachining process, the layer fabricated between the mechanical layer and the underlying layer. This layer is removed after fabrication. If cuts are designed in this sacrificial layer (as shown in Fig. 2),

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² *Annual Book of ASTM Standards*, Vol 03.01.